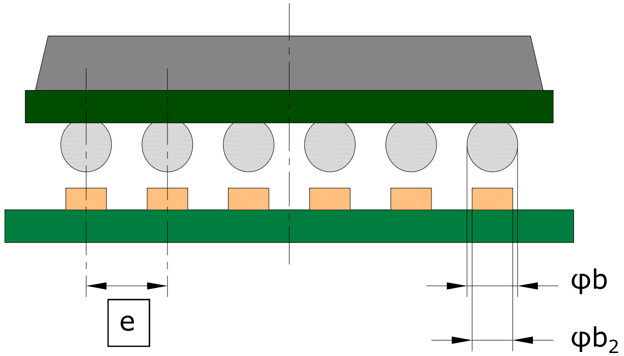
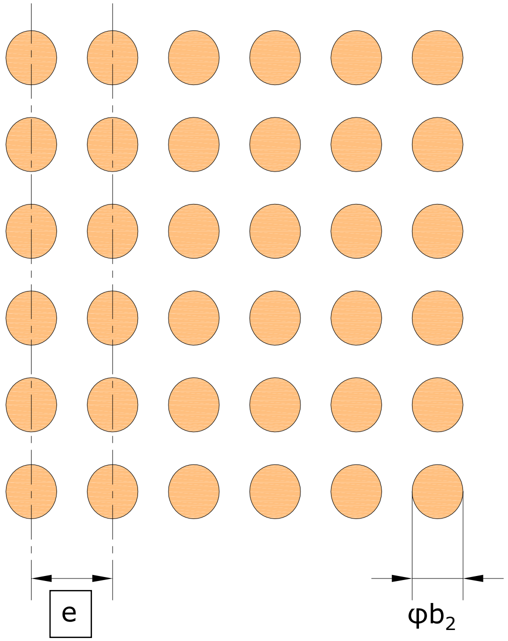
BGA,LGA
Mount Pad Dimensions





○ Dimension parameter

Lead pitch (mm) | e |	1.50	1.27	1.00	0.80	0.75	0.65	0.50	0.40
Dimension value φ (mm) φb_2	0.55 to 0.65	0.55 to 0.65	0.45 to 0.55	0.35 to 0.45	0.25 to 0.35	0.30 to 0.40	0.20 to 0.30	0.15 to 0.25

Note
Generally about BGA and LGA, to distribute solder joint stress equally to joint , the size of mount pad should be the same as the land diameter of packages.